

SN74LV05A オープン・ドレイン出力、ヘキサ・インバータ

1 特長

- 2V~5.5V の V_{CC} で動作
- 標準 V_{OLP} (出力グランド・バウンス)
 $< 0.8V$ ($V_{CC} = 3.3V$, $T_A = 25^\circ C$)
- 標準 V_{OHV} (出力 V_{OH} アンダーシュート)
 $> 2.3V$ ($V_{CC} = 3.3V$, $T_A = 25^\circ C$)
- すべてのポートで混在モード電圧動作をサポート
- I_{off} により部分的パワーダウン・モードでの動作をサポート
- JESD 17 準拠で 250mA 超のラッチアップ性能

2 アプリケーション

- 電子 POS
- I/O モジュール: アナログ PLC/DCS 入力
- モータ駆動および制御
- サーバー
- ネットワーク・スイッチ
- 試験および測定機器

3 説明

SN74LV05A デバイスは、2V~5.5V の V_{CC} で動作するように設計された 6 つの独立したインバータを備えています。

このデバイスは、ブール関数 $Y = \bar{A}$ を実行します。

パッケージ情報⁽¹⁾

部品番号	パッケージ	本体サイズ (公称)
SN74LV05A	DGV (TVSOP, 14)	3.60mm × 4.40mm
	D (SOIC, 14)	8.65mm × 3.91mm
	NS (SO, 14)	10.30mm × 5.30mm
	PW (TSSOP, 14)	5.00mm × 4.40mm

- (1) 利用可能なパッケージについては、このデータシートの末尾にある注文情報を参照してください。



簡略回路図



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision J (December 2014) to Revision K (March 2023) Page

- ドキュメント全体を通して表、図、相互参照のフォーマットを更新し、DB パッケージへの参照を削除..... **1**

Changes from Revision I (April 2005) to Revision J (December 2014) Page

- 「アプリケーション」、「デバイス情報」表、「ピンの機能」表、「ESD 定格」表、「熱に関する情報」表、「代表的特性」、「機能説明」セクション、「デバイスの機能モード」、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、および「メカニカル、パッケージ、および注文情報」セクションを追加..... **1**
- 「注文情報」表を削除..... **1**
- MAX operating temperature to 125°C in *Recommended Operating Conditions* table..... **5**

5 Pin Configuration and Functions

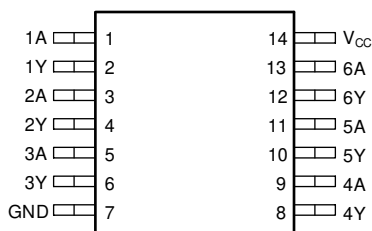


图 5-1. D, DGV, NS, or PW Package (Top View)

表 5-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NO.	NAME		
1	1A	I	1A Input
2	1Y	O	1Y Output
3	2A	I	2A Input
4	2Y	O	2Y Output
5	3A	I	3A Input
6	3Y	O	3Y Output
7	GND	—	Ground Pin
8	4Y	O	4Y Output
9	4A	I	4A Input
10	5Y	O	5Y Output
11	5A	I	5A Input
12	6Y	O	6Y Output
13	6A	I	6A Input
14	V _{CC}	—	Power Pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	–0.5	7	V
V _I	Input voltage range ⁽²⁾	–0.5	7	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	–0.5	7	V
V _O	Output voltage range ^{(2) (3)}	–0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		–20 mA
I _{OK}	Output clamp current	V _O < 0		–50 mA
I _O	Continuous output current	V _O = 0 to V _{CC}		±25 mA
	Continuous current through V _{CC} or GND			±50 mA
T _J	Junction temperature			150 °C
T _{stg}	Storage temperature range	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under [セクション 6.3](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 5.5-V maximum.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge		
	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	2500	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	2000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.7		
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.7		
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7		
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5	V
		V _{CC} = 2.3 V to 2.7 V		V _{CC} × 0.3	
		V _{CC} = 3 V to 3.6 V		V _{CC} × 0.3	
		V _{CC} = 4.5 V to 5.5 V		V _{CC} × 0.3	
V _I	Input voltage		0	5.5	V
V _O	Output voltage		0	5.5	V
I _{OL}	Low-level output current	V _{CC} = 2 V		50	μA
		V _{CC} = 2.3 V to 2.7 V		2	
		V _{CC} = 3 V to 3.6 V		6	
		V _{CC} = 4.5 V to 5.5 V		12	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 2.3 V to 2.7 V		200	ns/V
		V _{CC} = 3 V to 3.6 V		100	
		V _{CC} = 4.5 V to 5.5 V		20	
T _A	Operating free-air temperature		–40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74LV05A				UNIT
		D	DGV	NS	PW	
		14 PINS				
R _{θJA}	Junction-to-ambient thermal resistance	94.9	130.4	91.4	122.6	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	56.3	53.4	49.0	51.3	
R _{θJB}	Junction-to-board thermal resistance	49.2	63.5	50.2	64.4	
Ψ _{JT}	Junction-to-top characterization parameter	20.7	7.3	15.3	6.8	
Ψ _{JB}	Junction-to-board characterization parameter	48.9	62.8	49.8	63.8	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OL}	Low-level output voltage	I _{OL} = 50 μA	2 V to 5.5 V		0.1		0.1		0.1	V
		I _{OL} = 2 mA	2.3 V		0.4		0.4		0.4	
		I _{OL} = 6 mA	3 V		0.44		0.44		0.44	
		I _{OL} = 12 mA	4.5 V		0.55		0.55		0.6	

6.5 Electrical Characteristics (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
I _I	Input leakage current	V _I = 5.5 V or GND			±1		±1		±1	μA
I _{CC}	Static supply current	V _I = V _{CC} or GND, I _O = 0			20		20		20	μA
I _{off}	Input/Output PowerOff Leakage Current	V _I or V _O = 0 to 5.5 V			5		5		5	μA
C _i	Input capacitance V	V _I = V _{CC} or GND		2.5						pF

6.6 Switching Characteristics, V_{CC} = 2.5 V ± 0.2 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF		3.6 ⁽¹⁾	10.4 ⁽¹⁾	1	13	1	13.5	ns
t _{PHL}					5.8 ⁽¹⁾	12.2 ⁽¹⁾	1	15	1	16.5	
t _{PLH}	A	Y	C _L = 50 pF		6.1	15.2	1	18	1	18.5	ns
t _{PHL}					8.1	16.6	1	19.5	1	21	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.7 Switching Characteristics, V_{CC} = 3.3 V ± 0.3 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF		2.9 ⁽¹⁾	7.1 ⁽¹⁾	1	8.5	1	9	ns
t _{PHL}					4 ⁽¹⁾	7.1 ⁽¹⁾	1	8.5	1	9.5	
t _{PLH}	A	Y	C _L = 50 pF		4.7	10.6	1	12	1	12.5	ns
t _{PHL}					5.8	10.6	1	12	1	13	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.8 Switching Characteristics, V_{CC} = 5 V ± 0.5 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF		2.2 ⁽¹⁾	5.5 ⁽¹⁾	1	6.5	1	7	ns
t _{PHL}					2.9 ⁽¹⁾	5.5 ⁽¹⁾	1	6.5	1	7.5	
t _{PLH}	A	Y	C _L = 50 pF		3.4	7.5	1	8.5	1	9	ns
t _{PHL}					4.2	7.5	1	8.5	1	9.5	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.9 Noise Characteristics

V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C

PARAMETER		SN74LV05A			UNIT
		MIN	TYP	MAX	
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.55	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		–0.04	–0.8	V

$V_{CC} = 3.3\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$

PARAMETER	SN74LV05A			UNIT
	MIN	TYP	MAX	
$V_{OH(V)}$ Quiet output, minimum dynamic V_{OH}		3.12		V
$V_{IH(D)}$ High-level dynamic input voltage	2.31			V
$V_{IL(D)}$ Low-level dynamic input voltage			0.97	V

6.10 Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd} Power dissipation capacitance	$C_L = 50\text{ pF}$ $f = 10\text{ MHz}$	3.3 V	2.5	pF
		5 V	3	

6.11 Typical Characteristics

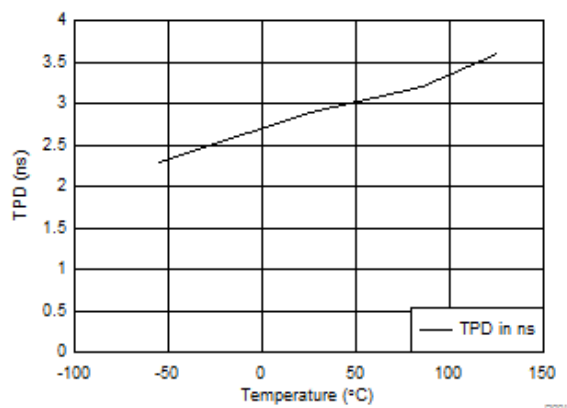


FIG 6-1. TPD vs Temperature

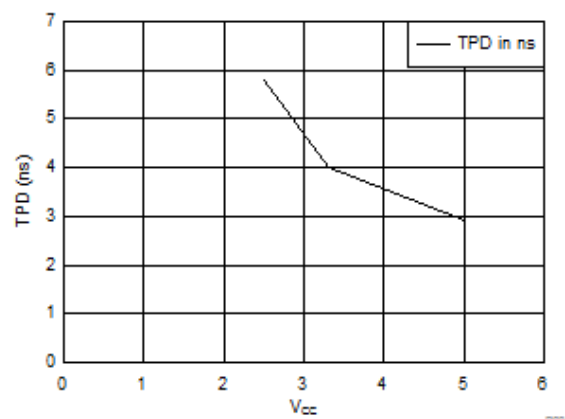
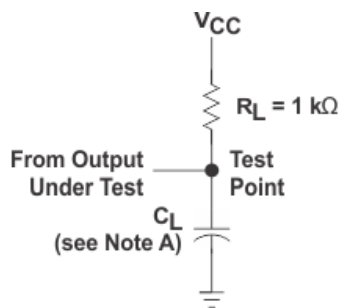
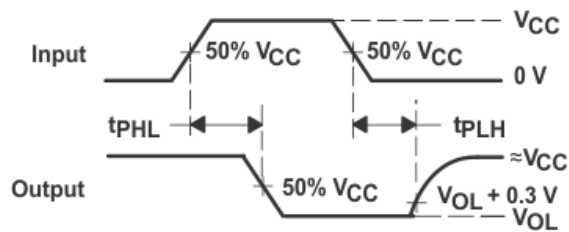


FIG 6-2. TPD vs V_{CC} at 25°C

7 Parameter Measurement Information



**LOAD CIRCUIT FOR
OPEN-DRAIN OUTPUTS**



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES**

- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
 C. The outputs are measured one at a time, with one input transition per measurement.

7-1. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The SN74LV05A device contains six independent inverters designed for 2-V to 5.5-V V_{CC} operation.

This device performs the Boolean function $Y = \bar{A}$.

The open-drain outputs require pull-up resistors to perform correctly and can be connected to other open-drain outputs to implement active-low, wired-OR or active-high wired-AND functions.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

8.2 Functional Block Diagram



图 8-1. Logic Diagram (Positive Logic)

8.3 Feature Description

- Wide operating voltage range
 - Operates from 2 V to 5.5 V
- Allows down-voltage translation
 - Inputs accept voltages to 5.5 V
- I_{off} feature
 - Allows voltages on the inputs and outputs when V_{CC} is 0 V

8.4 Device Functional Modes

表 8-1. Function Table
(Each Inverter)

INPUT ⁽¹⁾ A	OUTPUT ⁽²⁾ Y
H	L
L	H

- (1) H = High Voltage Level, L = Low Voltage Level, X = Don't Care
- (2) H = Driving High, L = Driving Low, Z = High Impedance State

9 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

9.1 Application Information

SN74LV05A is a low-drive, open-drain CMOS device that can be used for a multitude of buffer type functions. The inputs are 5.5-V tolerant and the outputs are open-drain and 5.5-V tolerant, allowing it to translate up to 5.5 V or down to any other voltage between GND and 5.5 V.

9.2 Typical Application

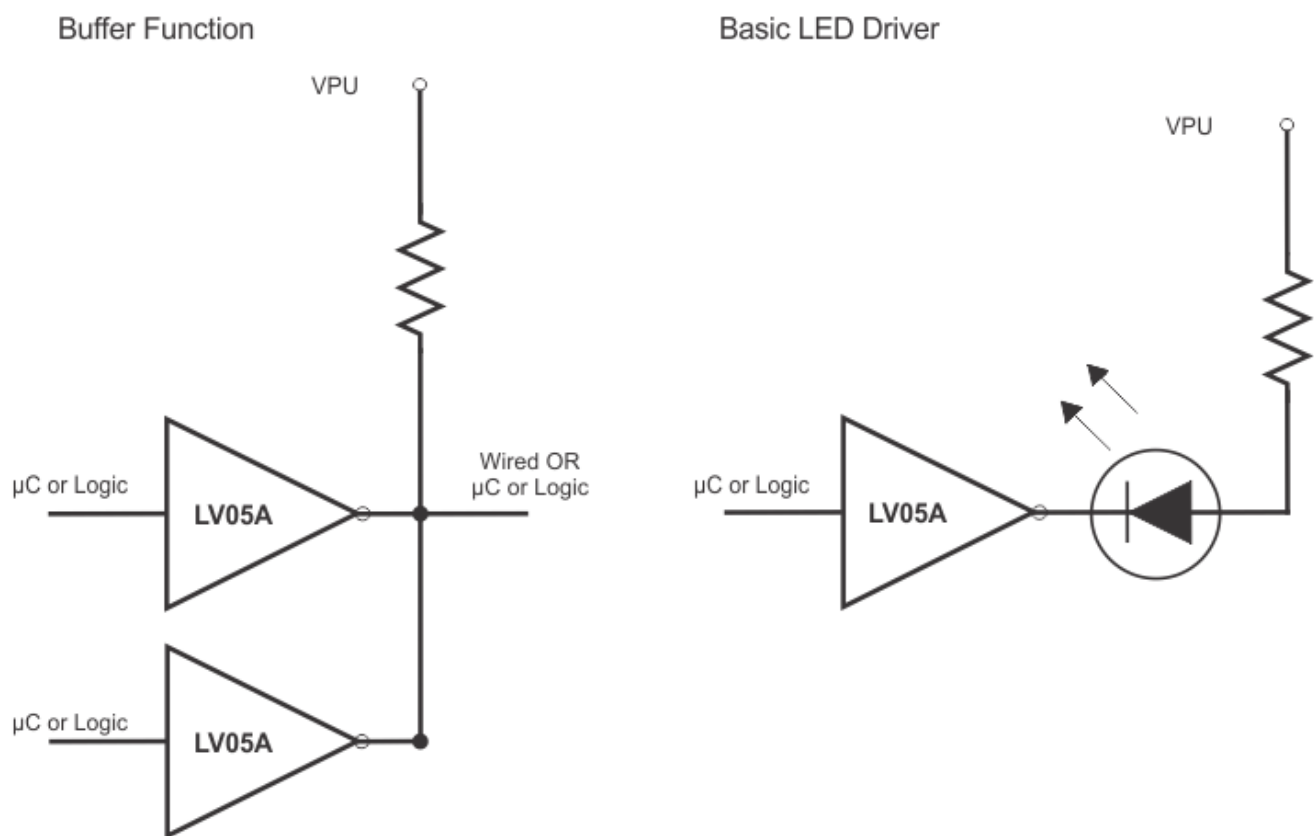


図 9-1. Typical Application Schematic

9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

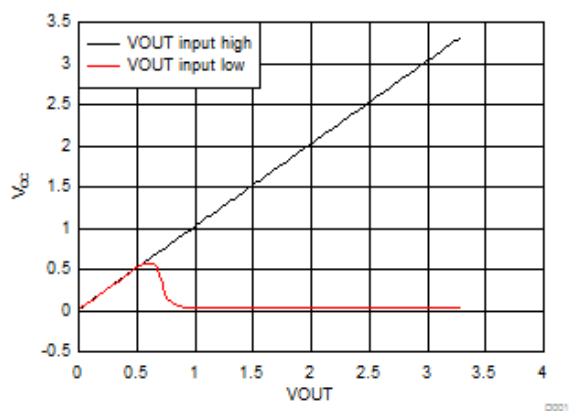
9.2.2 Detailed Design Procedure

1. Recommended Input Conditions

- For rise time and fall time specifications, see $\Delta t/\Delta V$ in the [セクション 6.3](#) table.
- For specified High and low levels, see V_{IH} and V_{IL} in the [セクション 6.3](#) table.

- Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC} .
2. Recommend Output Conditions
- Load currents should not exceed 35 mA per output and 50 mA total for the part.

9.2.3 Application Curves



9-2. Output at Power Up with 4k Pull-Up 3.3 V

9.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [セクション 6.3](#) table.

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 μF is recommended. If there are multiple V_{CC} pins, 0.01 μF or 0.022 μF is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 μF and 1 μF are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

9.4 Layout

9.4.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [図 9-3](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver.

9.4.2 Layout Example

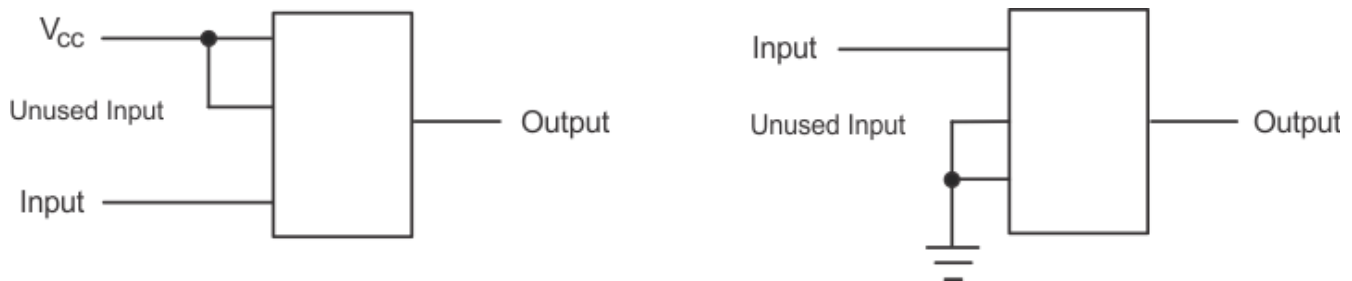


図 9-3. Layout Diagram

10 Device and Documentation Support

10.1 Documentation Support

10.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 10-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LV05A	Click here	Click here	Click here	Click here	Click here

10.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](#) のデバイス製品フォルダを開いてください。「更新の通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

10.3 サポート・リソース

TI E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

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10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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10.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

10.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LV05AD	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-40 to 125	LV05A
SN74LV05ADGVR	Active	Production	TVSOP (DGV) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV05A
SN74LV05ADGVR.A	Active	Production	TVSOP (DGV) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV05A
SN74LV05ADR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV05A
SN74LV05ADR.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV05A
SN74LV05ANSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV05A
SN74LV05ANSR.A	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV05A
SN74LV05APW	Obsolete	Production	TSSOP (PW) 14	-	-	Call TI	Call TI	-40 to 125	LV05A
SN74LV05APWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(L05A, LV05A)
SN74LV05APWR.A	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(L05A, LV05A)
SN74LV05APWRG4	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV05A
SN74LV05APWT	Obsolete	Production	TSSOP (PW) 14	-	-	Call TI	Call TI	-40 to 125	LV05A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

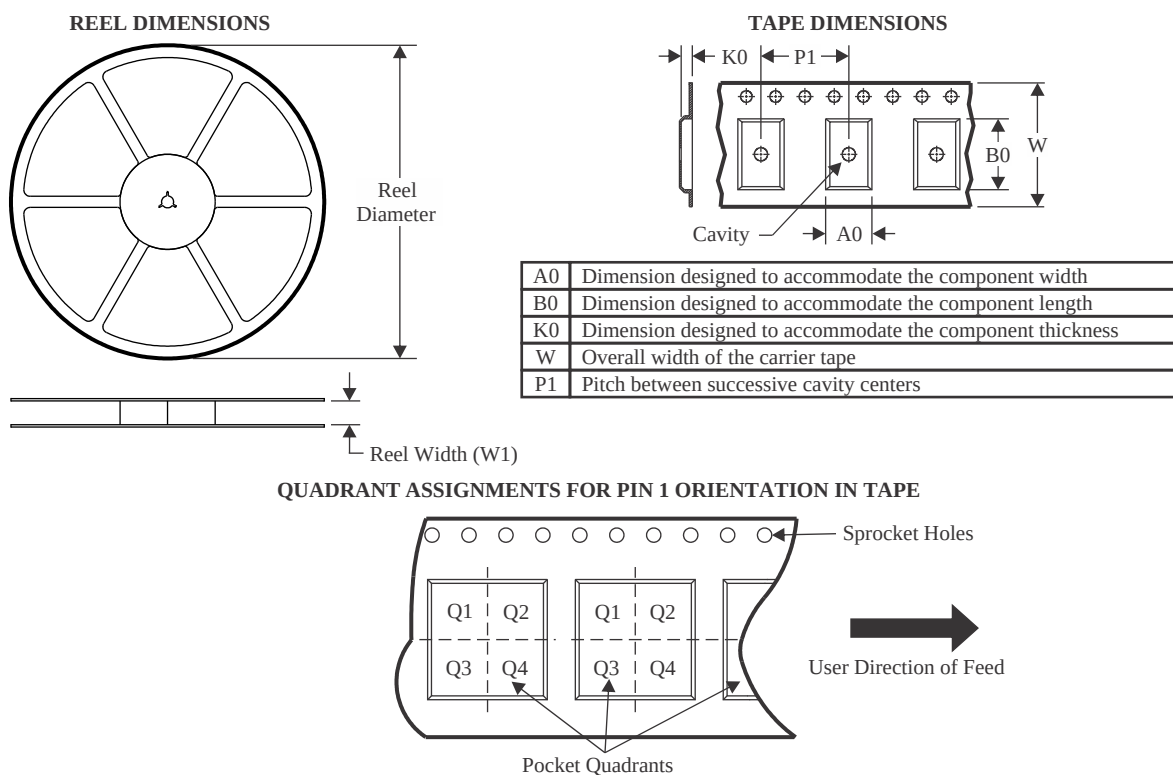
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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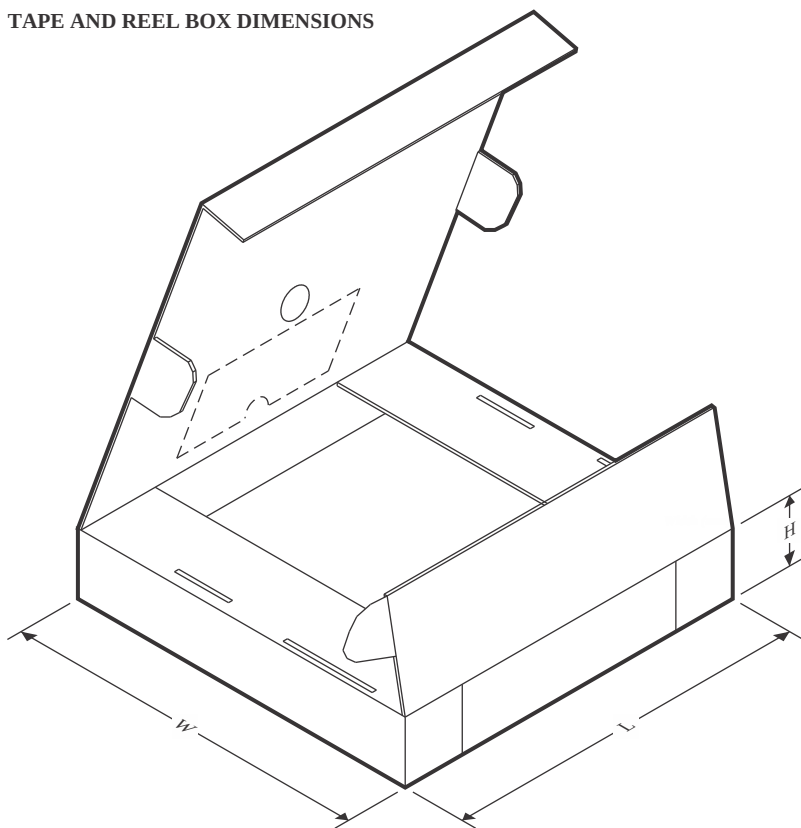
TAPE AND REEL INFORMATION



*All dimensions are nominal

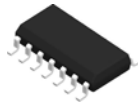
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV05ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV05ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV05ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV05APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV05APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV05APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

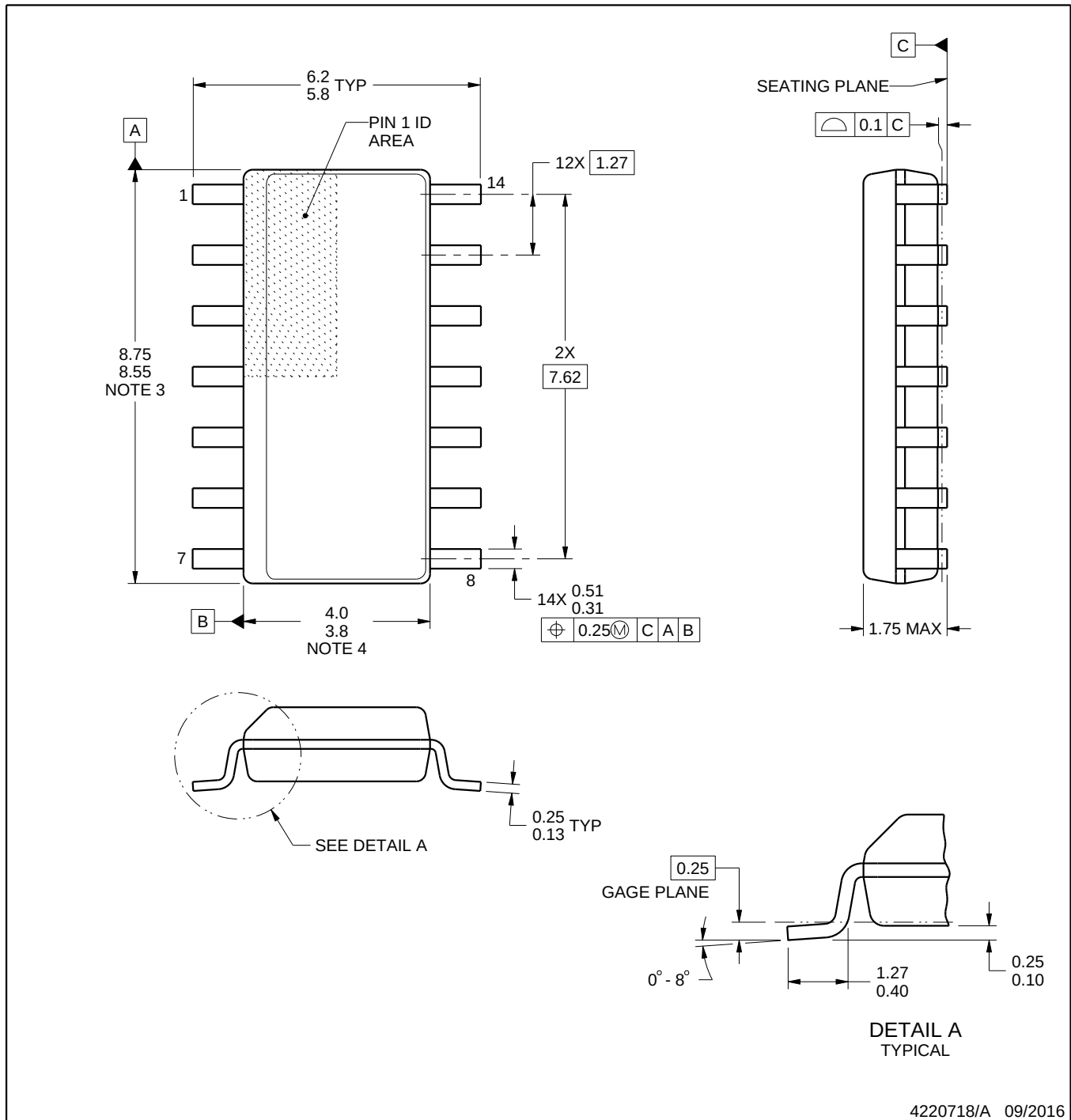


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV05ADGVR	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74LV05ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LV05ANSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74LV05APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LV05APWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74LV05APWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0

D0014A**PACKAGE OUTLINE****SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT

**NOTES:**

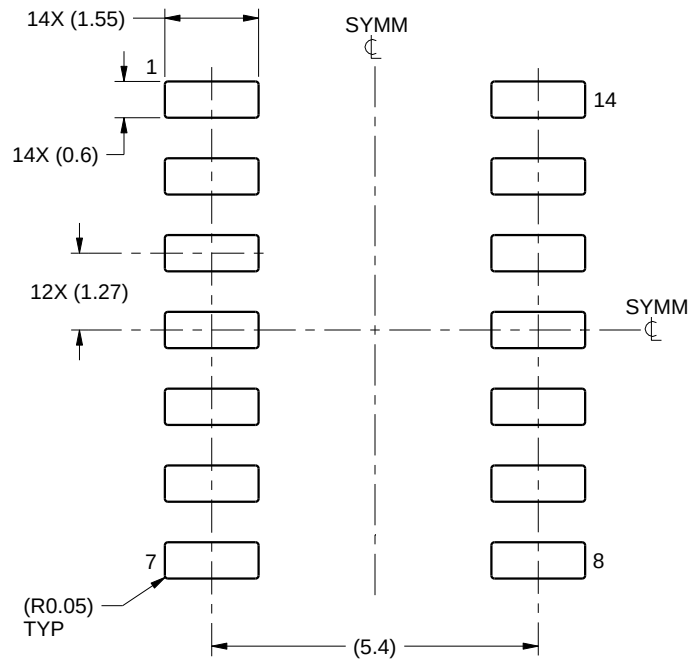
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

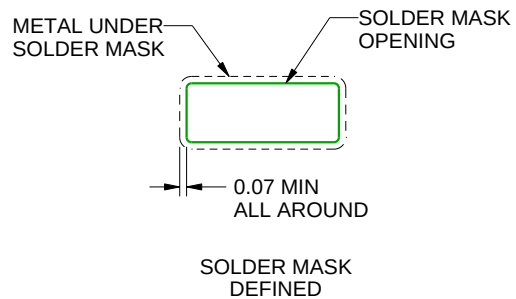
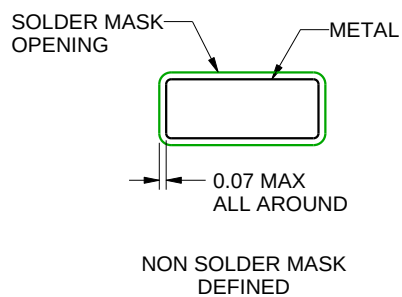
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

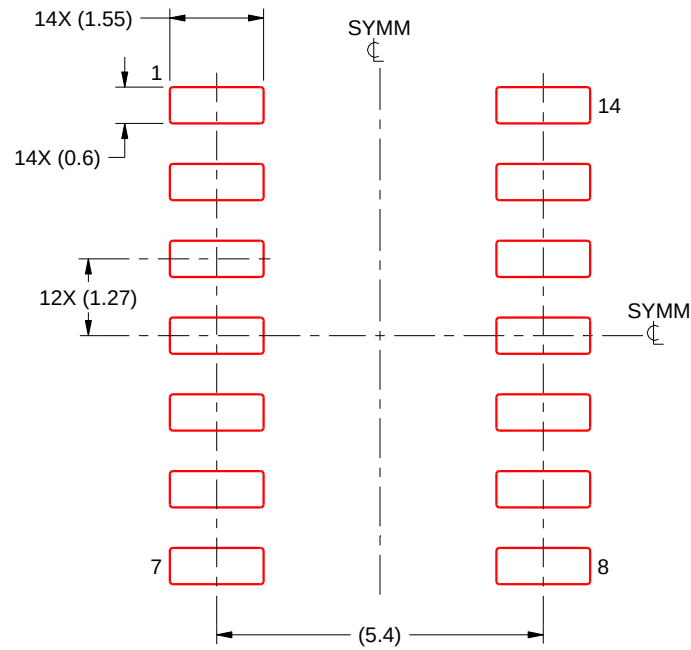
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

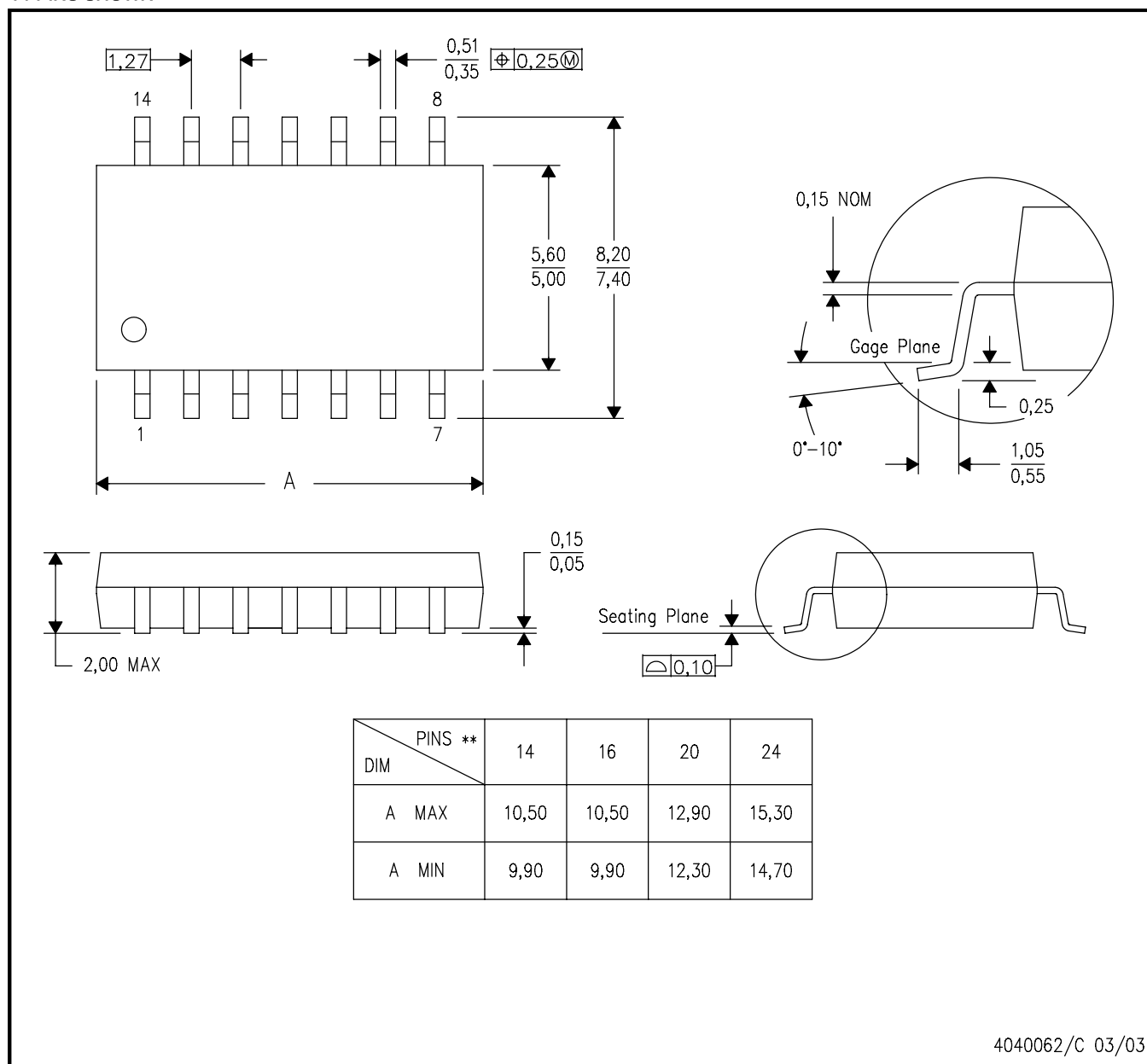
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



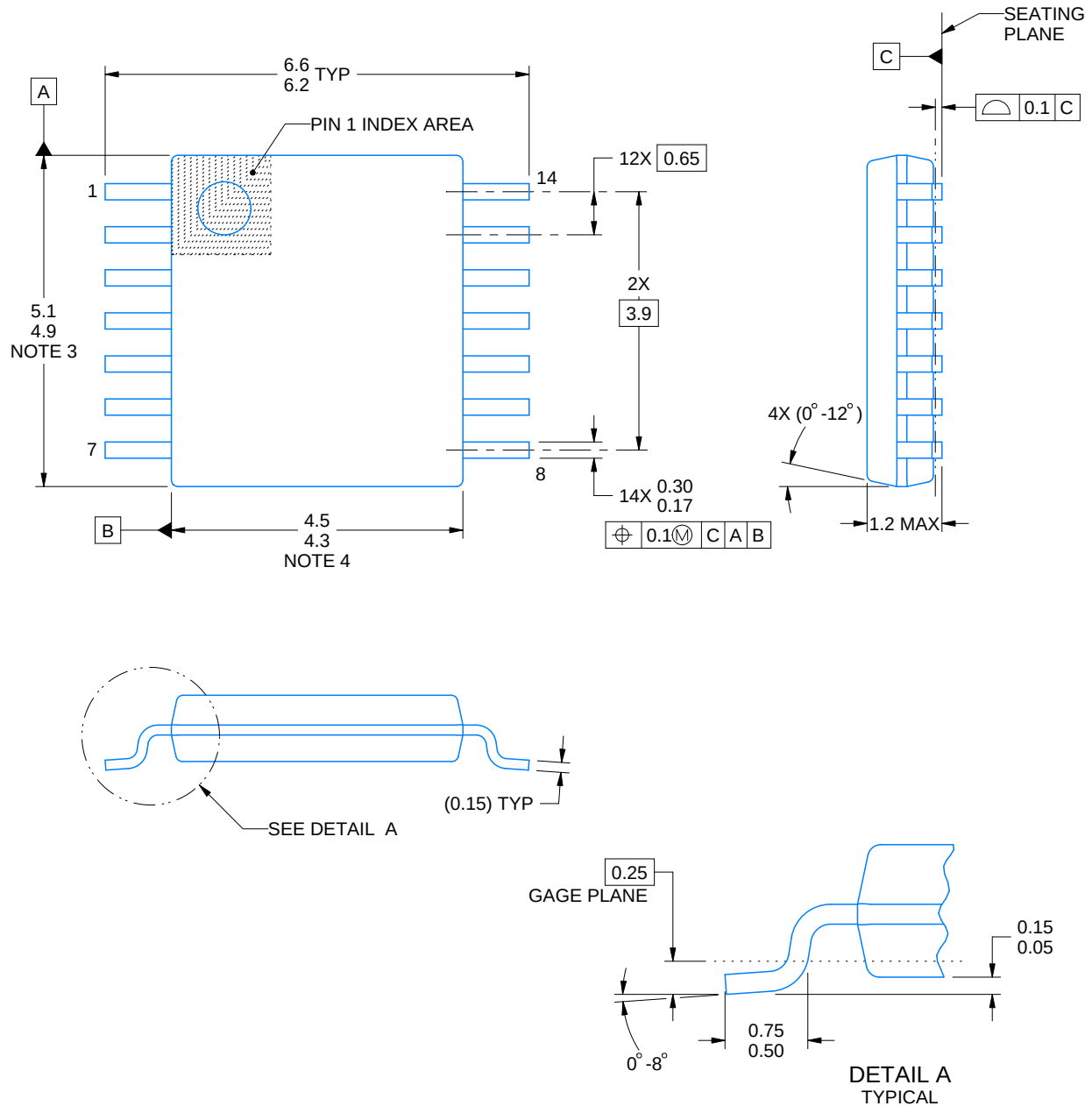
- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW0014A

PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

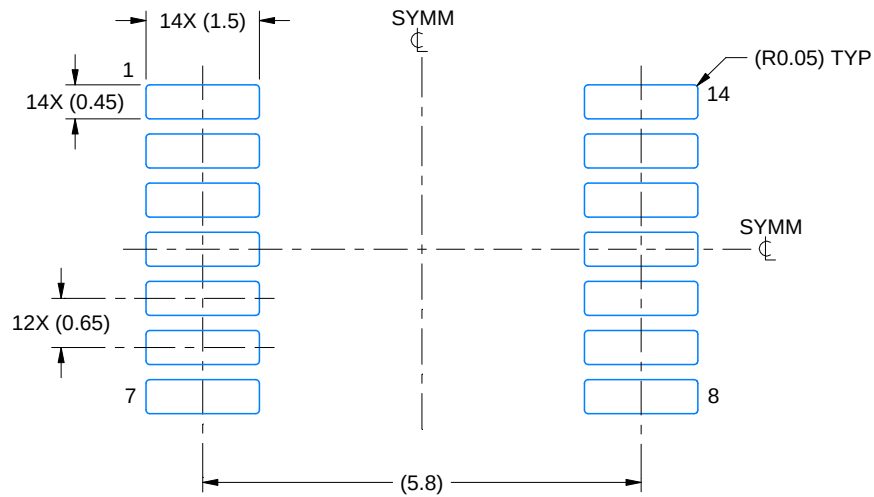
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

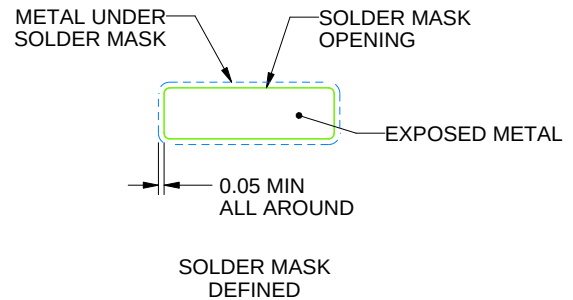
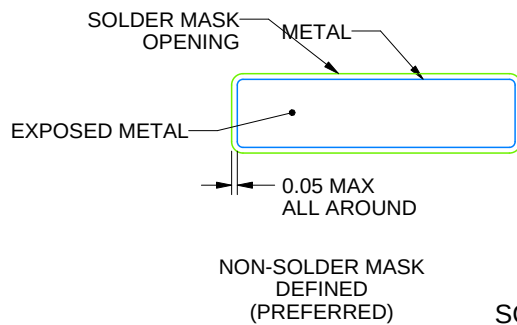
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

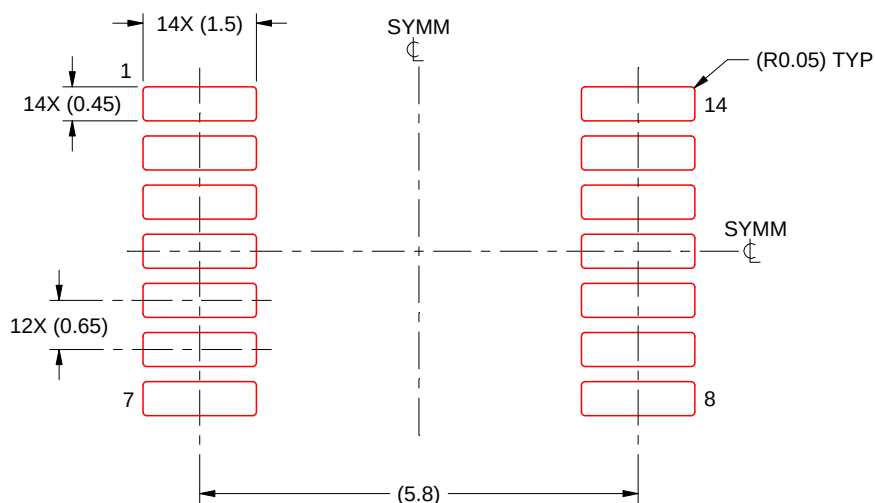
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

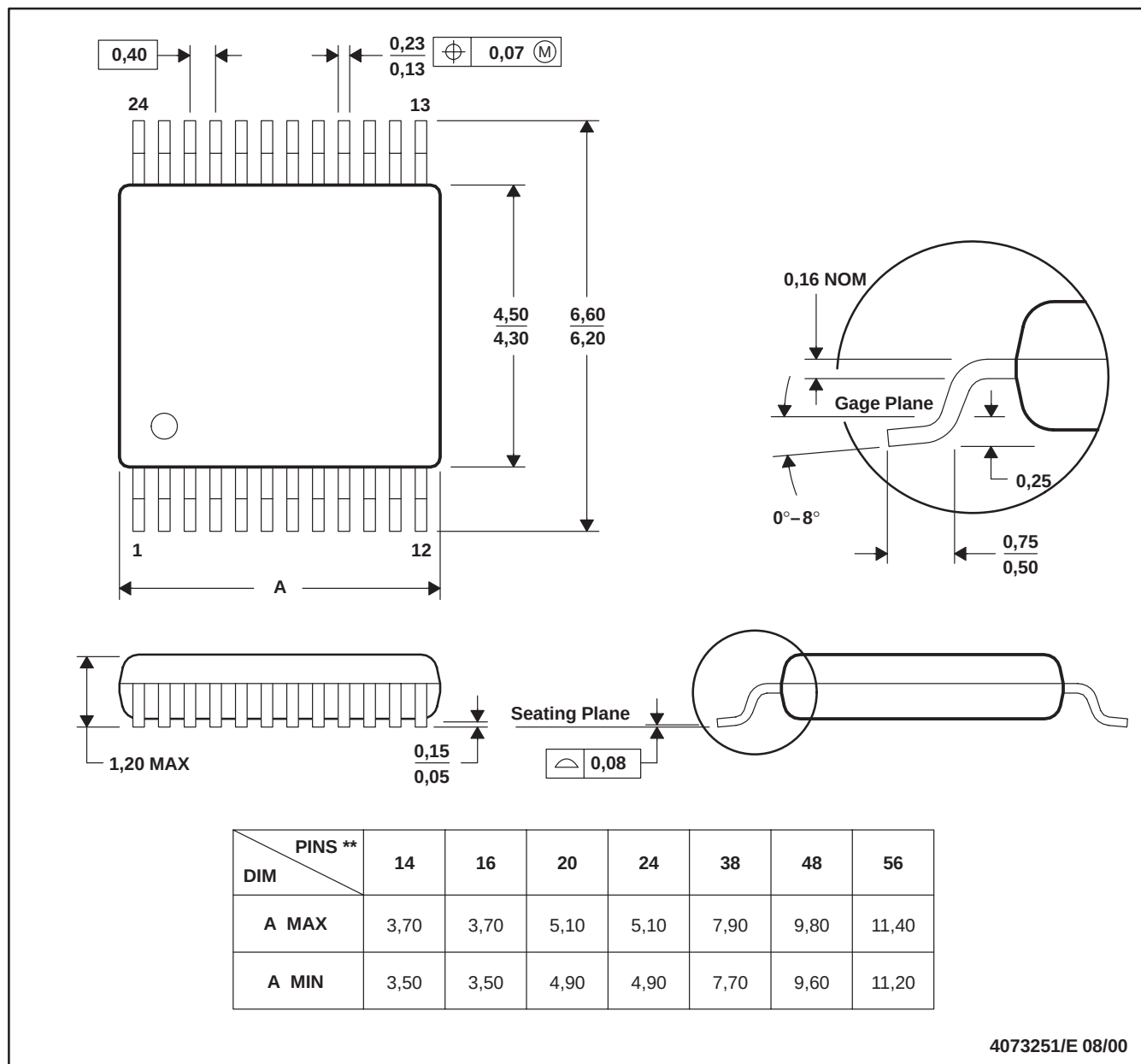
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

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